Low Power Peak Reducing EMI Solution

Description

The ASM3P2879A is a versatile spread spectrum frequency modulator designed specifically for a wide range of clock frequencies. The ASM3P2879A reduces electromagnetic interference (EMI) at the clock source, allowing system wide reduction of EMI of all clock dependent signals. The ASM3P2879A allows significant system cost savings by reducing the number of circuit board layers, ferrite beads and shielding that are traditionally required to pass EMI regulations.

The ASM3P2879A uses the most efficient and optimized modulation profile approved by the FCC and is implemented by using a proprietary all digital method.

The ASM3P2879A modulates the output of a single PLL in order to "spread" the bandwidth of a synthesized clock, and more importantly, decreases the peak amplitudes of its harmonics. This results in significantly lower system EMI compared to the typical narrow band signal produced by oscillators and most frequency generators. Lowering EMI by increasing a signal's bandwidth is called 'spread spectrum clock generation.'

Applications

The ASM3P2879A is targeted towards all portable devices with very low power requirements like MP3 players, Notebooks and digital still cameras.

Features

- Generates an EMI Optimized Clock Signal at the Output
- Integrated Loop Filter Components
- Operates with a 3.3 V / 2.5 V Supply
- Operating Current less than 4 mA
- Low Power CMOS Design
- Input Frequency Range:

13 MHz to 30 MHz for 2.5 V

13 MHz to 30 MHz for 3.3 V

- Generates a 1X Low EMI Spread Spectrum Clock of the Input Frequency
- Frequency Deviation: ±1% @ 24 MHz
- Available in 6-pin TSOT-23, 8-pin SOIC and 8-pin TSSOP Packages
- These Devices are Pb–Free, Halogen Free/BFR Free and are RoHS Compliant



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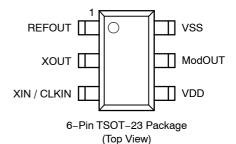


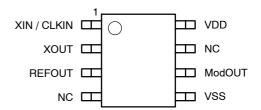




TSOT-6 O SUFFIX CASE 419AF TSSOP-8 T SUFFIX CASE 948AL SOIC-8 S SUFFIX CASE 751BD

PIN CONFIGURATIONS





8-Pin SOIC and TSSOP Packages (Top View)

KEY SPECIFICATIONS

Description	Specification
Supply Voltages	VDD = 2.5 V / 3.3 V
Cycle-to-Cycle Jitter	200 pS (Max)
Output Duty Cycle	45/55%
Modulation Rate Equation	F _{IN} /640
Frequency Deviation	±1% @ 24 MHz

ORDERING INFORMATION

See detailed ordering and shipping information in the package dimensions section on page 10 of this data sheet.

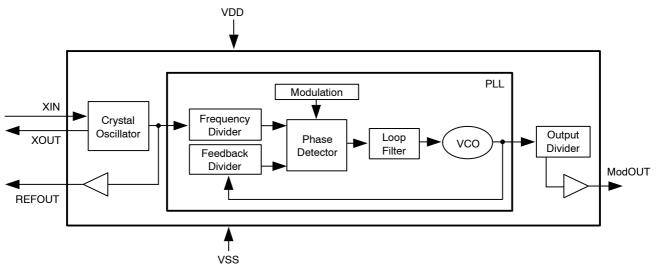


Figure 1. Block Diagram

Table 1. PIN DESCRIPTION (6-Pin TSOT-23 Package)

Pin#	Pin Name	Туре	Description
1	REFOUT	0	Buffered output of the input frequency.
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.
3	XIN / CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
4	VDD	Р	Power supply for the entire chip (3.3 V).
5	ModOUT	0	Spread spectrum clock output.
6	VSS	Р	Ground connection.

Table 2. PIN DESCRIPTION (8-Pin SOIC and TSSOP Packages)

Pin#	Pin Name	Type	Description
1	XIN / CLKIN	I	Crystal connection or external reference frequency input. This pin has dual functions. It can be connected either to an external crystal or an external reference clock.
2	XOUT	0	Crystal connection. If using an external reference, this pin must be left unconnected.
3	REFOUT	0	Buffered output of the input frequency.
4	NC	_	No connect.
5	VSS	Р	Ground connection.
6	ModOUT	0	Spread spectrum clock output.
7	NC	_	No connect.
8	VDD	Р	Power supply for the entire chip.

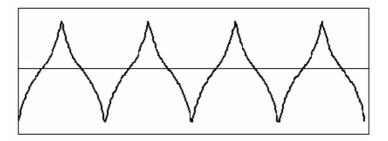


Figure 2. Modulation Profile

Table 3. SPECIFICATIONS

Description		Specification
Frequency Range	For 2.5 V Supply	13 MHz < CLKIN < 30 MHz
	For 3.3 V Supply	
Modulation Equation		F _{IN} /640
Frequency Deviation		±1% @ 24 MHz

Table 4. ABSOLUTE MAXIMUM RATINGS

Symbol	Parameter	Rating	Unit
VDD, V _{IN}	Voltage on any pin with respect to Ground	-0.5 to +4.6	V
T _{STG}	Storage temperature	-65 to +125	°C
T _A	Operating temperature	-40 to +85	°C
T _s	Max. Soldering Temperature (10 sec)	260	°C
T _J	Junction Temperature	150	°C
T _{DV}	Static Discharge Voltage (As per JEDEC STD22- A114-B)	2	KV

Stresses exceeding Maximum Ratings may damage the device. Maximum Ratings are stress ratings only. Functional operation above the Recommended Operating Conditions is not implied. Extended exposure to stresses above the Recommended Operating Conditions may affect device reliability.

Table 5. DC ELECTRICAL CHARACTERISTICS FOR 2.5 V SUPPLY

(Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated.)

Symbol	Parameter	Min	Тур	Max	Unit
V _{IL}	Input low voltage	VSS-0.3	=	0.8	V
V _{IH}	Input high voltage	2.0	=	VDD+0.3	V
I _{IL}	Input low current	-	-	-35	μΑ
I _{IH}	Input high current	-	-	35	μΑ
I _{XOL}	XOUT output low current (@ 0.5 V, VDD = 2.5 V)	-	3	-	mA
I _{XOH}	XOUT output high current (@ 1.8 V, VDD = 2.5 V)	-	3	-	mA
V _{OL}	Output low voltage (VDD = 2.5 V, I _{OL} = 8 mA)	-	-	0.6	V
V _{OH}	Output high voltage (VDD = 2.5 V, I _{OH} = 8 mA)	1.8	-	-	V
I _{DD}	Static supply current (Note 1)	-	1.2	-	mA
I _{CC}	Dynamic supply current (2.5 V, 24 MHz and with no load)	-	3.5	-	mA
VDD	Operating Voltage	2.375	2.5	2.625	V
t _{ON}	Power-up time (first locked cycle after power-up)	-	-	5	mS
Z _{OUT}	Output impedance	-	50	_	Ω

^{1.} XIN / CLKIN pin is pulled low.

Table 6. AC ELECTRICAL CHARACTERISTICS FOR 2.5 V SUPPLY

Symbol	Parameter		Min	Тур	Max	Unit
CLKIN	Input frequency		13	-	30	MHz
ModOUT	Output frequency		13	-	30	MHz
f _d	Frequency Deviation	Input Frequency = 13 MHz	=	±1.75	-	%
		Input Frequency = 30 MHz	=	±0.80	-	
t _{LH} (Note 2)	Output rise time (measured fro	om 0.7 V to 1.7 V)	0.8	1.7	1.9	nS
t _{HL} (Note 2)	Output fall time (measured from 1.7 V to 0.7 V)		0.5	0.9	1.2	nS
tuc	Jitter (Cycle-to-Cycle)		=	-	200	pS
t _D	Output duty cycle		45	50	55	%

^{2.} t_{LH} and t_{HL} are measured into a capacitive load of 15 pF.

Table 7. DC ELECTRICAL CHARACTERISTICS FOR 3.3 V SUPPLY

(Test condition: All parameters are measured at room temperature (+25°C) unless otherwise stated.)

Symbol	Parameter	Min	Тур	Max	Unit
V _{IL}	Input low voltage	VSS-0.3	-	0.8	V
V _{IH}	Input high voltage	2.0	-	VDD+0.3	V
I _{IL}	Input low current	-	-	-35	μΑ
I _{IH}	Input high current	-	-	35	μΑ
I _{XOL}	XOUT output low current (@ 0.4 V, VDD = 3.3 V)	-	3	-	mA
I _{XOH}	XOUT output high current (@ 2.5 V, VDD = 3.3 V)	-	3	-	mA
V _{OL}	Output low voltage (VDD = 3.3 V, I _{OL} = 8 mA)	-	-	0.4	V
V _{OH}	Output high voltage (VDD = 3.3 V, I _{OH} = 8 mA)	2.5	-	-	V
I _{DD}	Static supply current (Note 3)	-	1.2	-	mA
I _{CC}	Dynamic supply current (3.3 V, 24 MHz and with no load)	-	4.5	-	mA
VDD	Operating Voltage	2.7	3.3	3.6	V
t _{ON}	Power-up time (first locked cycle after power-up)	-	-	5	mS
Z _{OUT}	Output impedance	-	45	-	Ω

^{3.} XIN / CLKIN pin is pulled low.

Table 8. AC ELECTRICAL CHARACTERISTICS FOR 3.3 V SUPPLY

Symbol	Para	Min	Тур	Max	Unit	
CLKIN	Input frequency		13	=	30	MHz
ModOUT	Output frequency		13	=	30	MHz
f _d	Frequency Deviation	Input Frequency = 13 MHz	=	±1.75	=	%
		Input Frequency = 30 MHz	=	±0.80	=	
t _{LH} (Note 4)	Output rise time (measured fro	om 0.8 V to 2.0 V)	0.6	1.6	1.8	nS
t _{HL} (Note 4)	Output fall time (measured at 2.0 V to 0.8 V)		0.4	1.0	1.2	nS
tuc	Jitter (Cycle-to-Cycle)		_	-	200	pS
t _D	Output duty cycle		45	50	55	%

^{4.} t_{LH} and t_{HL} are measured into a capacitive load of 15 pF.

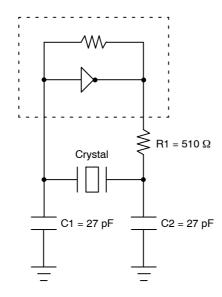


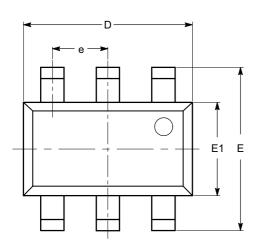
Figure 3. Typical Crystal Oscillator Circuit

Table 9. TYPICAL CRYSTAL SPECIFICATIONS

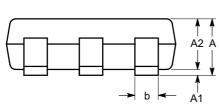
Fundamental AT Cut Parallel Resonant Crystal				
Nominal frequency	14.31818 MHz			
Frequency tolerance	±50 ppm or better at 25°C			
Operating temperature range	-25°C to +85°C			
Storage temperature	-40°C to +85°C			
Load capacitance	18 pF			
Shunt capacitance	7 pF maximum			
ESR	25 Ω			

PACKAGE DIMENSIONS

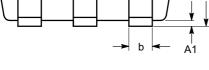
TSOT-23, 6 LEAD CASE 419AF-01 ISSUE O



TOP	VIEW
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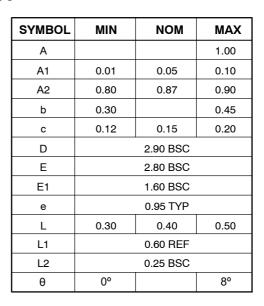


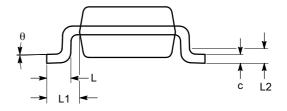
SIDE VIEW





(2) Complies with JEDEC MO-193.

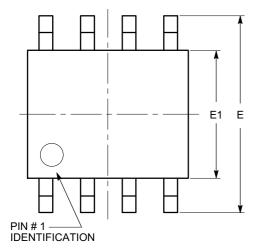




END VIEW

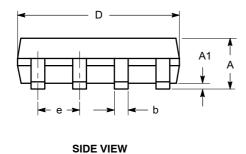
PACKAGE DIMENSIONS

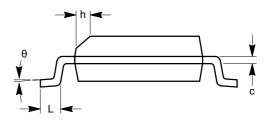
SOIC 8, 150 mils CASE 751BD-01 ISSUE O



SYMBOL	MIN	NOM	MAX
Α	1.35		1.75
A1	0.10		0.25
b	0.33		0.51
С	0.19		0.25
D	4.80		5.00
E	5.80		6.20
E1	3.80		4.00
е		1.27 BSC	
h	0.25		0.50
L	0.40		1.27
θ	0°		8°

TOP VIEW





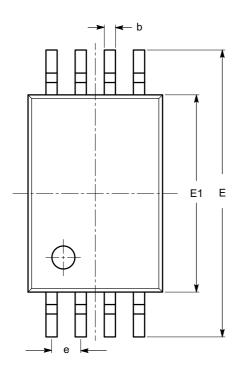
END VIEW

Notes:

- (1) All dimensions are in millimeters. Angles in degrees.
- (2) Complies with JEDEC MS-012.

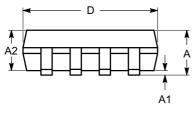
PACKAGE DIMENSIONS

TSSOP8, 4.4x3 CASE 948AL-01 ISSUE O

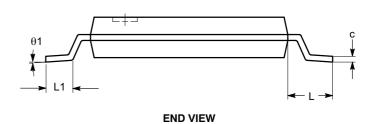


SYMBOL	MIN	NOM	MAX
Α			1.20
A1	0.05		0.15
A2	0.80	0.90	1.05
b	0.19		0.30
С	0.09		0.20
D	2.90	3.00	3.10
E	6.30	6.40	6.50
E1	4.30	4.40	4.50
е	0.65 BSC		
L	1.00 REF		
L1	0.50	0.60	0.75
θ	0°		8°





SIDE VIEW



Notes:

- (1) All dimensions are in millimeters. Angles in degrees.(2) Complies with JEDEC MO-153.

Table 10. ORDERING INFORMATION

Part Number	Marking	Package Type	Temperature
ASM3P2879AF-06OR	D4LL	6-Pin TSOT-23, TAPE & REEL, Pb Free	Commercial
ASM3P2879AF-08TT	3P2879AF	8-Pin TSSOP, TUBE, Pb Free	Commercial
ASM3P2879AF-08TR	3P2879AF	8-Pin TSSOP, TAPE & REEL, Pb Free	Commercial
ASM3P2879AF-08ST	3P2879AF	8-Pin SOIC, TUBE, Pb Free	Commercial
ASM3P2879AF-08SR	3P2879AF	8-Pin SOIC, TAPE & REEL, Pb Free	Commercial
ASM3P2879AG-06OR	D3LL	6-Pin TSOT-23, TAPE & REEL, Green	Commercial
ASM3P2879AG-08TT	3P2879AG	8-Pin TSSOP, TUBE, Green	Commercial
ASM3P2879AG-08TR	3P2879AG	8-Pin TSSOP, TAPE & REEL, Green	Commercial
ASM3P2879AG-08ST	3P2879AG	8-Pin SOIC, TUBE, Green	Commercial
ASM3P2879AG-08SR	3P2879AG	8-Pin SOIC, TAPE & REEL, Green	Commercial
ASM3I2879AF-06OR	D5LL	6-Pin TSOT-23, TAPE & REEL, Pb Free	Industrial
ASM3I2879AF-08TT	3l2879AF	8-Pin TSSOP, TUBE, Pb Free	Industrial
ASM3I2879AF-08TR	3l2879AF	8-Pin TSSOP, TAPE & REEL, Pb Free	Industrial
ASM3I2879AF-08ST	3l2879AF	8-Pin SOIC, TUBE, Pb Free	Industrial
ASM3I2879AF-08SR	3l2879AF	8-Pin SOIC, TAPE & REEL, Pb Free	Industrial
ASM3I2879AG-06OR	D6LL	6-Pin TSOT-23, TAPE & REEL, Green	Industrial
ASM3I2879AG-08TT	3l2879AG	8-Pin TSSOP, TUBE, Green	Industrial
ASM3I2879AG-08TR	3l2879AG	8-Pin TSSOP, TAPE & REEL, Green	Industrial
ASM3I2879AG-08ST	3l2879AG	8-Pin SOIC, TUBE, Green	Industrial
ASM3I2879AG-08SR	3l2879AG	8-Pin SOIC, TAPE & REEL, Green	Industrial

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